

2 **Developing Firmware and Algorithms for the Liquid** 3 **Argon Signal Processor**

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10 **ABSTRACT:** In this report we discuss the development of various firmware and algorithms for the
11 digital electronics of the Liquid Argon Signal Processor (LASP), which is designed to measure and
12 reconstruct the energy deposited into the Liquid Argon Calorimeter cells. We first examine the
13 development of firmware for PATGEN, TTCGEN, 10Gbe Base R/KR network protocols. Then we
14 explore the development of novel machine learning algorithms for optimal energy reconstruction
15 given the digital current signals. Lastly, we investigate various hardware tests to examine the
16 functionality of the future electronic boards.

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54 **1 Introduction**

55 The ATLAS (A Toroidal LHC ApparatuS) detector is one of the four main particle detectors at the
56 Large Hadron Collider (LHC), which is the world’s largest and most powerful particle accelerator
57 located at CERN (the European Organization for Nuclear Research) near Geneva, Switzerland.

58 The main purpose of the ATLAS detector is to observe and study the particles produced by
59 high-energy proton-proton collisions in the LHC. This detector works by detecting various kinds
60 of particles in 4 main sections.

61 Firstly, the innermost part of the ATLAS detector is the tracking system, which consists of
62 semiconductor-based detectors like silicon strips and pixels. When charged particles pass through
63 these sensors, they ionize the material, creating electron-hole pairs that generate electrical signals.
64 These signals allow the tracking system to reconstruct the paths of charged particles, determining
65 their momentum and charge.

66 Next we have the Electromagnetic Calorimeter (ECal) which is designed to measure the energy
67 of electrons and photons. When these particles pass through the ECal, they interact with its dense
68 material, producing electromagnetic showers. The energy of the original particle can be measured
69 by the the ionization signal inside the calorimeter.

70 Then surround that we have the Hadronic Calorimeter (HCal) which is used to measure the
71 energy of hadrons, such as protons, neutrons, and mesons. Hadrons interact strongly with matter
72 and create hadronic showers when they pass through the HCal. The energy of the original particle
73 is measured by the total amount of hadronic activity in this calorimeter.

74 Lastly, we have the Muon Spectrometer. Muons are particles that can penetrate through several
75 layers of the detector due to their weak interactions with matter. The outermost part of the ATLAS
76 detector is the muon spectrometer, which consists of large magnet systems and dedicated tracking
77 chambers. It is used to precisely measure the trajectories and momenta of muons, which are essential
78 for various physics analyses, including the discovery of the Higgs boson.

79 Together with these sub-detectors, the ATLAS detector provides a comprehensive view of the
80 particles produced in LHC collisions, allowing physicists to explore and understand the fundamental
81 constituents of matter and the forces that govern them.

82 **1.1 Liquid Argon Calorimeter and Electronics**

83 The Liquid Argon Calorimeter is specifically responsible for detecting and measuring the electro-
84 magnetic showers produced by electrons and photons as they interact with the detector’s material.
85 These showers are cascades of secondary particles generated when high-energy electrons or photons
86 lose energy.

87 The active medium, liquid argon, is an ionizable material. When charged particles, such as
88 electrons or positrons, enter the liquid argon they ionize the atoms along their path, producing
89 charged particles (electrons and ions) within the LAr.

90 The ionization produced in the liquid argon generates electrical current and thus a measurable
91 signal. These signals are collected by the readout electrodes in the gaps between the lead absorber
92 plates. The readout electrodes are made of copper and are surrounded in the liquid argon. By
93 measuring the ionization signals, the ECal can determine the energy deposited by the electrons and
94 photons in the calorimeter.

95 The Liquid Argon Calorimeter employs a sampling technique, where the dense absorber
96 material (lead) causes electromagnetic showers to develop, while the liquid argon serves as the
97 active medium to detect and measure the energy of the showering particles. This method allows for
98 accurate energy measurements while also containing the size of the calorimeter.

99 However, the electrical signals measured on the readout electrodes are weak and need to
100 be amplified and shaped before further processing. Front-end electronics, located close to the
101 calorimeter, perform this initial amplification and shaping of the signals.

102 After being amplified and shaped, the analog current signals are digitized. Analog-to-digital
103 converters (ADCs) convert the continuous analog signals into digital values, which can be easily
104 processed and recorded by digital systems. This entire process is handled by the Front End Boards
105 (FEB). In the future the FEB will be upgraded to the FEB2.

106 Then, we transmit the data to the digital signal processor where the final step in the liquid argon
107 signal processing is the reconstruction of the energy deposited by the particles in the calorimeter.
108 To achieve such goal, we need to develop custom electronics to meet the demands for the future
109 upgraded High Luminosity Large Hadron Collider, to handle the increased data rate. This new
110 electronics, involve software, firmware and hardware developments on Field programmable Gate
111 Arrays. We will spend the majority of our development and discussion on building and improving
112 this component of the calorimeter called the Liquid Argon Signal Processor (LASP).

113 **1.2 High Luminosity Large Hadron Collider (HL-LHC)**

114 The HL-LHC upgrade is aimed at significantly increasing the collision rate and the overall luminosity
115 of the LHC by a factor of 5-10, which refers to the number of particle collisions occurring per unit
116 of time and per unit of area. This increase in luminosity is crucial for enhancing the chances of
117 discovering new particles or phenomena and for conducting more precise measurements of known
118 particles. However this upgrade comes with many new challenges, of which pileup and new trigger
119 systems are critically important motivators to upgrade the current LAr Calorimeters.

120 Pileup: Pileup refers to the phenomenon that occurs when multiple proton-proton collisions
121 take place simultaneously in a single bunch crossing in a particle accelerator like the LHC. In
122 other words, when two high-energy proton beams collide head-on, each bunch of protons contains
123 a certain number of protons, and each proton can interact with another proton from the opposing
124 beam. However, due to the high luminosity of the LHC, there's a possibility that multiple protons
125 from one bunch can interact with protons from another bunch at the same time. This results in
126 several independent interactions occurring in one bunch crossing.

127 Pileup becomes more significant as the luminosity of the accelerator increases, this in part is
128 due to the higher number of interactions per bunch crossing on the order of 200 as opposed to 40 in
129 the current LHC. High pileup levels can pose challenges to particle detectors and analysis because
130 it becomes harder to distinguish the particles coming from different interactions. This can impact
131 the accuracy of measurements and make it more difficult to identify rare or interesting events.

132 In terms of the new Trigger Systems, particle accelerators like the LHC generate a tremendous
133 amount of data from each collision, and not all of this data can be processed and stored due to
134 limitations in computing resources. To address this, trigger systems are employed. Trigger systems
135 are specialized hardware and software designed to quickly decide which collision events are worth
136 recording for further analysis.

137 The HL-LHC upgrade involves the development of new trigger systems to handle the increased
138 number of interactions per bunch crossing. This means that it is more difficult to identify quickly
139 the particles we want to have as a final state and hence the events to select. This is in turn a result of
140 increased pileup. The new trigger systems aim to be more sophisticated and selective in choosing
141 which events to record. Here are some aspects of the new trigger systems.

142 Together with other upgrade challenges we see that critical electronics such as those for the LAr
143 need to be upgraded as well to match the new demands of the HL - LHC both with the new trigger
144 scheme and for the high pileup as well upgrading the hardware to hold the more computationally
145 intensive firmware. This new upgrade for the LAr is called the Liquid Argon Phase-II upgrade.
146 Even more specifically we look to upgrade the Liquid Argon Signal Processor (LASP) to address
147 these new challenges.

148 **1.3 Overview**

149 For the LASP upgrade there are few major components that need to be upgraded and developed.
150 This falls under 3 big categories, firmware, energy reconstruction algorithms and functional tests.
151 In the remaining sections we discuss 5 major projects working towards advancing each of these
152 categories in various smaller projects.

153 1. **Firmware:** is the development of custom circuits on digital electronics to process incom-
154 ing data. The LASP is primarily programmed by writing firmware on these FPGA (field
155 programmable gate arrays). Below are few firmware projects that we have developed this
156 summer.

157 (a) **PATGEN:** stands for Pattern Generator and is a piece of firmware designed to generate
158 FEB2 equivalent data internally without having to connect to a FEB2 board.

159 (b) **TTCGEN** stands for the TTC (Trigger Timing Control) generator which generates inter-
160 nally TTC equivalent data without having to be connected to the outside world.

161 (c) **10 GB BASE-KR** is a new implementation of the 10GB network stack that uses the
162 BASE-KR PHY layer instead of the original BASE-R PHY layer [1].

163 2. **Energy Reconstruction Algorithms** are algorithms on the LASP used to convert digital
164 current measurements to estimations on energy. In this project we investigate the use of
165 machine learning algorithms to help with energy reconstruction in high pileup environments.

166 3. **Functional Tests:** we also prototype circuits and software for reading current and voltage
167 measurements on the LASP boards. These are designed to test the functionality of the
168 manufactured hardware.

169 Together all these projects help contribute to the development of LASP board for the planned Phase
170 II upgrades.

171 **2 Background**

172 **2.1 FPGA's and Firmware**

173 An FPGA, stands for Field-Programmable Gate Array, is a type of integrated circuit that is pro-
174 grammable and reconfigurable after manufacturing. Unlike traditional application-specific inte-
175 grated circuits (ASICs) that are designed for specific tasks, FPGAs can be customized and adapted
176 for various applications through hardware programming called firmware programming.

177 FPGA's offer attractive advantages for our LASP use case in that 1) Flexibility: They can be
178 easily reprogrammed to implement different logic functions or algorithms, making them adaptable
179 for various applications. 2) High performance: In certain scenarios, FPGAs can provide faster
180 processing compared to software running on a general-purpose CPU. 3) Real-time processing:
181 FPGAs are well-suited for real-time applications due to their ability to process data in parallel.

182 The principle of firmware programming is that it is a description of *circuits* rather than *code*
183 like in a procedural program. By default signals are sent in parallel, but in order to implement
184 procedural logic, clocked processes are vital. For every component we time the manipulation of
185 signals to the cycles of a clock. This way one can reasonably program and synchronize the various
186 parallel processes in their firmware. This clocked process can also be called a flipflop. With this
187 principle in mind, one can leverage the power of these fabless boards for realtime processing!

188 The general cycle of development with firmware follows as such: 1) firstly we implement the
189 algorithm in VHDL (Very High-Speed Integrated Circuit Hardware Description Language) code
190 2) we simulate the code in a testbench simulation to verify it works as intended 3) we write the
191 component onto a development kit FPGA and finally we write to the LASP testboard and use signal
192 tap to verify its functionality.

193 This summer we build upon the existing LASP firmware upgrade to implement more transparent
194 testing components for future development.

195 **2.2 Energy Reconstruction and the Optimal Filter**

196 In addition of the firmware side of the LASP, the actual algorithm in reconstructing the digital signal
197 is vital as well. The signal processor needs to take in ADC data and convert it into an estimation in
198 the energies of an event. Currently, to do so we use the Optimal Filter (OF).

199 The OF is a linear filter. The filter works by taking a set of constant coefficients to which we
200 then multiply and sum with the incoming ADC data. These static coefficients are found through
201 minimizing a least squares fit between the model and the simulated data. This technique is currently
202 favoured due to its interpretability, accuracy and efficient implementation on a FPGA.

203 Although this has proven to be successful, there are new challenges that are not present for the
204 current ATLAS detector, namely pileup.

205 Pileup occurs when the collision rate is high, which is expected in the HL-LHC. In these
206 scenarios, particles produced from single collision can still be present or interacting within the
207 detector when subsequent collisions occur. These collisions occur at every 25. For the LAr, this is
208 due to the delay caused by the time it takes for electrons to drift across the liquid argon gap creating
209 a pileup of signal since. In other words the signal does not disappear fast enough before the next
210 collision occurs, hence creating an increased amount of pileup.

211 This poses a problem for the OF since this super position of signal creates noise making
212 inaccurate reconstruction of energy. Furthermore, even if we refit the optimal filter to the high
213 pileup data expected for the HL-LHC the simple linear filter still is insufficient in recreating the
214 original energy signal accurately due to the noisy low energy pileup.

215 Previously, attempts have been made to improve the linear filter through the use of various neural
216 networks, and other non-linear filter techniques. This summer we investigated new approaches to
217 this problem using machine learning beyond that of convolution neural networks and recurrent
218 neural networks.

219 **2.3 Hardware Boards and Testing**

220 Lastly, regardless of the firmware and software engineering involved we also need to develop
221 robust hardware to run the LASP on. We anticipate the hardware to eventually be manufactured by
222 third-party vendors like Intel and physical links developed by members of the ATLAS collaboration.

223 However, to determine the functionality of these hardware boards we need to develop physical
224 probes to test the hardware. One of the proposed ideas is to develop user friendly software to
225 interface with measurement tools such that engineers on the ground can quickly determine the
226 functionality of a given manufactured board. This allows for faster turnarounds.

227 **3 Firmware**

228 **3.1 Introduction Firmware Programming and LASP Framework**

229 Programming an FPGA involves designing and configuring the hardware logic within the FPGA
230 to perform a specific task or function. These devices are versatile in that they allow one to define
231 one's own digital logic circuits, making them suitable for a wide range of applications. The process
232 involves several steps, from designing the logic using a hardware description language (HDL) to
233 actually programming the FPGA device. We quickly walk through how this is typically done for
234 the LASP project.

235 For the LASP project, the firmware is based in VHDL and tested, developed and deployed
236 to Intel based silicone. Because of these restrictions we make use of Intel's Quartus Prime 22.4,
237 Intel's IP Cores and their suite of simulation and programming tools to implement our design and
238 our workflow.

239 Using these Intel provided software tools, the LASP project builds a framework to help
240 accelerate the design and testing of these projects by connecting all various dependencies and sub
241 repositories through various symbolic links. This means that when using the LASP repository,
242 everything from simulations to compilations to even opening up quartus is done through `MAKE`
243 commands which automatically pulls in dependencies from the larger LASP project.

244 On a macro-scale, the LASP project consists of many components responsible for various tasks
245 in the digital signal processing pipeline. Each coloured box 1 represents a component of the LASP.
246 These components live as sub-repositories within the LASP repository project.

247 As evident by the number of coloured boxes, this firmware is quite complex. When developing
248 firmware we start with VHDL code of a component in isolation and slowly integrate complexity
249 into a particular component of the project. We then simulate the newly created components and

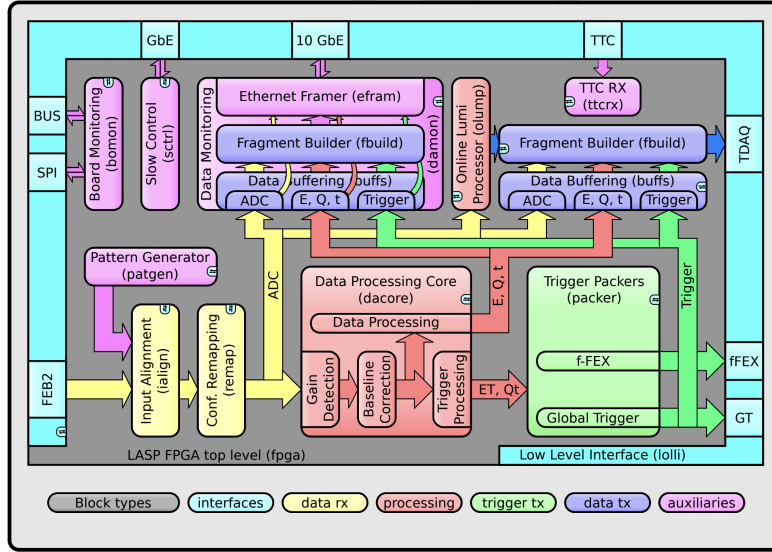


Figure 1. Diagram of all LASP Components

250 verify it's behaviour is correct. Beyond verifying by eye, we can verify using automated checks
 251 called UVVM (Universal VHDL Verification Methodology). UVVM checks are checked by the
 252 continuous integration (CI) in the LASP repository such that any merged code will need to pass
 253 these checks to be accepted into a master branch. Lastly, one would implement a compilation target
 254 that uses the component that we have created. This compilation target should also include signal
 255 tap which allows one to verify the internal signals of a particular component after writing it to an
 256 FPGA. This way it allows us to investigate the internal signals of the FPGA in realtime. The devices
 257 that we run on are the INTEL H-TILE STRATIX 10 DEVELOPMENT KITS with some of our work also
 258 having a LASP testboard (closer to real electronics deployed in the future) compilation target.

259 With this design, simulate, compile, test framework in mind, we move on to developing 3
 260 components of the LASP, namely PATGEN in section 3.2, TTCGEN in section 3.3 and 10GBE BASE-
 261 KR network stack in section 3.4.

262 3.2 PATGEN

263 Pattern Generator (patgen) is a component designed to provide a FEB2-equivalent data generator
 264 [2]. This is an important component dedicated to testing and ensuring all subsequent components
 265 of the LASP is functioning properly with testable mock data.

266 To understand what kind of data PATGEN needs to mimic, we need to understand where the data
 267 comes from. The FEB2 stands for the Front End Board 2 where 2 is the indication for phase 2
 268 upgrades [3]. The FEB2 houses the electronics that are mounted close to the detector.

269 These boards in particular receive the signals from the calorimeter cells to perform a fast analog
 270 processing, including amplification, shaping and a split into a high gain and a low gain [2]. Both
 271 gain are digitized by an ADC.

272 After the FEB2, the data is now a digital signal ready to be sent off detector optically. This is
 273 done through the lpGBT [4]. The LPGBT (Low Power GigaBit Transceiver) is a high-speed data

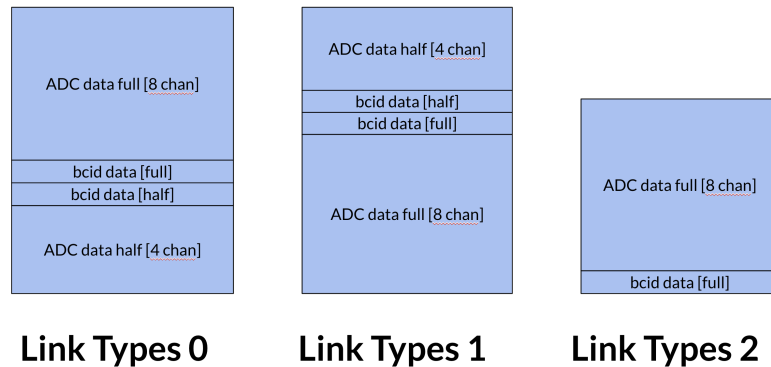


Figure 2. Example of link types 0,1, 2.

274 transmission and reception device made to provide reliable and high-speed data communication
 275 in harsh radiation environments. This connection has 14 channels of inputs unlike the 8 output
 276 channels of the FEB2.

277 However there is a complication, the mappings between the ADC chips with data coming out
 278 of the FEB2 versus that number of lpGBT boards is a mapping of 3 to 2. To support this there are
 279 3 specific link types (named 0, 1, 2 [2]) to complete such an awkward map.

280 In link type 0, 1, it includes 1.5 of a complete FEB2 ADC data output with 2 BCID (bunch
 281 crossing id) signals for each FEB2 output. In link type 2 it contains just 1 ADC data output. Note
 282 that each FEB2 outputs 8 channels of ADC data, so a full FEB2 has 8 ADC channels while half
 283 has 4. More specifically we expect signals to look like the following incoming from the FEB2, see
 284 diagram 2.

285 Our goal is to mimic this design and make it modular to allow future development of more
 286 complex data payloads.

287 3.2.1 Requirements

288 The more explicit requirements of PATGEN are outlined in the firmware specifications document [2],
 289 but are repeated here for readers to easily follow.

- 290 1. The data provided by patgen must have the same structure as the data from the FEB2s
- 291 2. Patgen must be able to mimic the non-synchronization between the links (BCID shift).
- 292 3. Each of the 66 links shall have an independent source of data.
- 293 4. A controllable multiplexer shall select between the two possible data sources (patgen or lolli's
 294 FEB2 interface) for ialign for each link individually.
- 295 5. Patgen as a data source shall be start- and stoppable,
- 296 6. While running it shall provide data in an uninterrupted, continuous and circular manner
- 297 7. The data repetition shall be compatible with an orbit (3564 BCs). (If resources require, a
 298 repetition twice or any integer fractions of an orbit are tolerable

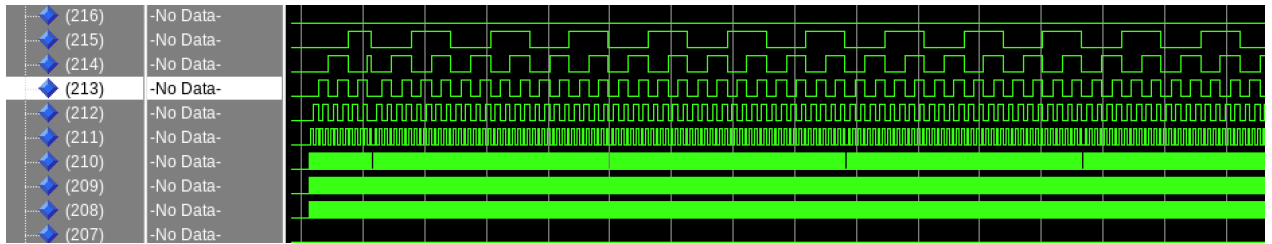


Figure 3. Example of an ADC channel implemented as a simple counter.

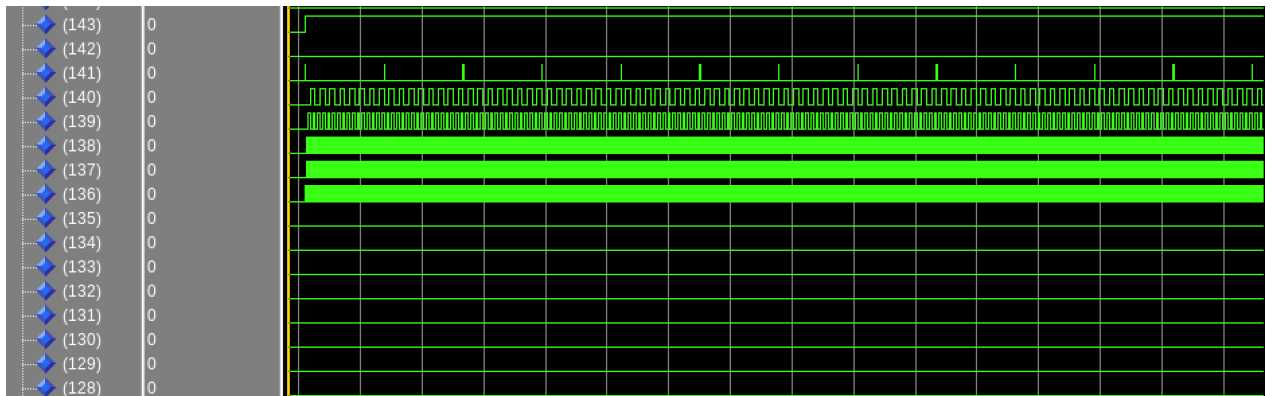


Figure 4. Example correctly formatted BCID info. Notice that the first bit is always 1, while the second bit is always 0 and the third bit is the BCR (bunch crossing reset) and the next five bits are the BCID followed by 8 bits of padded zeros.

299 3.2.2 Simulation

300 Firstly, to simulate PATGEN, we need to firstly generate a valid ADC data. For our simulation setup
 301 we will generate mock ADC data from a simple counter. We chose to use a simple counter as the
 302 mock ADC data because it makes it simple to debug future firmware components [2]. Below is a
 303 demonstration of utilizing a counter in figure 3.

304 Secondly we need to format the BCID information to the correct standards. We need the first
 305 bit to be 1 the second bit to be 0, the third bit to represent the BCR (bunch crossing reset) and the
 306 next 5 bits to represent the truncated BCID and the remain 8 bits to be padded with 0 [2]. Below is
 307 a demonstration of that in figure 4

308 Thirdly, we need to make sure all the link types are of the correct format. There are three link
 309 types, each representing the combination of full and half ADC data. Recall that an ADC data has
 310 8 channels, and a half ADC has 4. We piece together a set of 12 channels based on this data to
 311 form the three link types. Below is a demonstration of one of those link type implementations in
 312 figure 5. Fourth, we have delay chains. One of the primary use cases for the PATGEN component
 313 is to use it to test the ialign module. The ialign module is used to align the inputs coming in from
 314 the FEB2 [2]. In this case we want to introduce artificial delays such that we can test the ialign
 315 module for such situation. Below we demonstrate the use of delay chains and subsequently the use

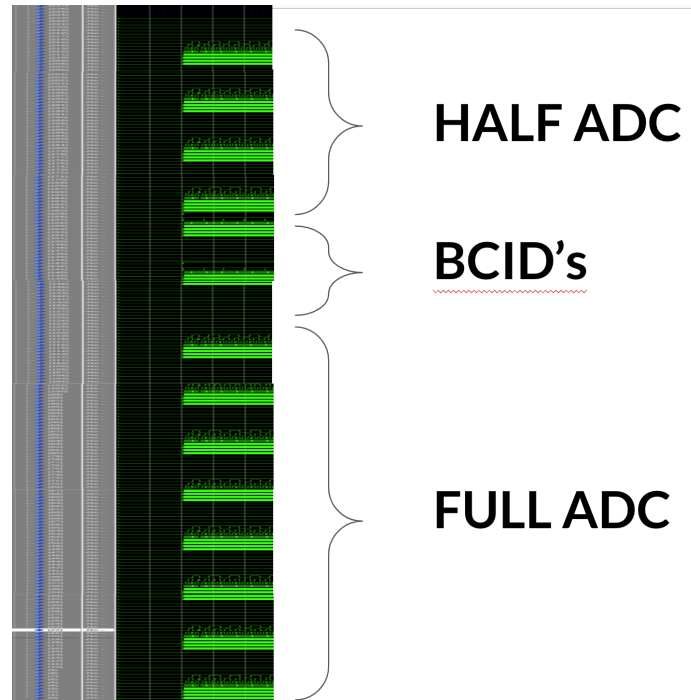


Figure 5. Example of linktype 0 which conforms to diagram 2. This appears to be flipped but keep in mind the simulation counts in reverse order.

316 of ialign with these delay chains. Fifth point is, we want to make sure that the ADC data orbits
 317 every fixed number of counts following the BCR [2]. This is because it makes debugging easier
 318 when observing the ADC data we can see it follows the same loop back. Last point, we have also
 319 implemented UVVM continuous integration checks for the PATGEN component. We check mainly
 320 for the regular counting of ADC and BCID data. We also count to keep track that the BCID loops
 321 back in the expected stated number of cycles.

322 3.2.3 Compilation

323 Finally having checked out the implementation in simulation we finally compile this to a particular
 324 target. This means writing to a particular FPGA and use a program called signal tap to check that
 325 the FPGA's internal signals are behaving in the correct fashion. Below in figure 8 we check signal
 326 tap on a compiled firmware and write it to the LASP testboard and observe the that the signals
 327 match that of the signals coming from the simulation. This verification is an indication that the
 328 written VHDL code is most likely correct.

329 3.2.4 Next Steps

330 The next step is to integrate PATGEN with other components in slice test beyond just the IALIGN
 331 component.

332 3.3 TTCGEN

333 The TTCGEN stands for TTC generator [2]. The TTC stands for Trigger Timing Control [3]. The
 334 TTC system provides the timing and trigger signals necessary to coordinate data acquisition and

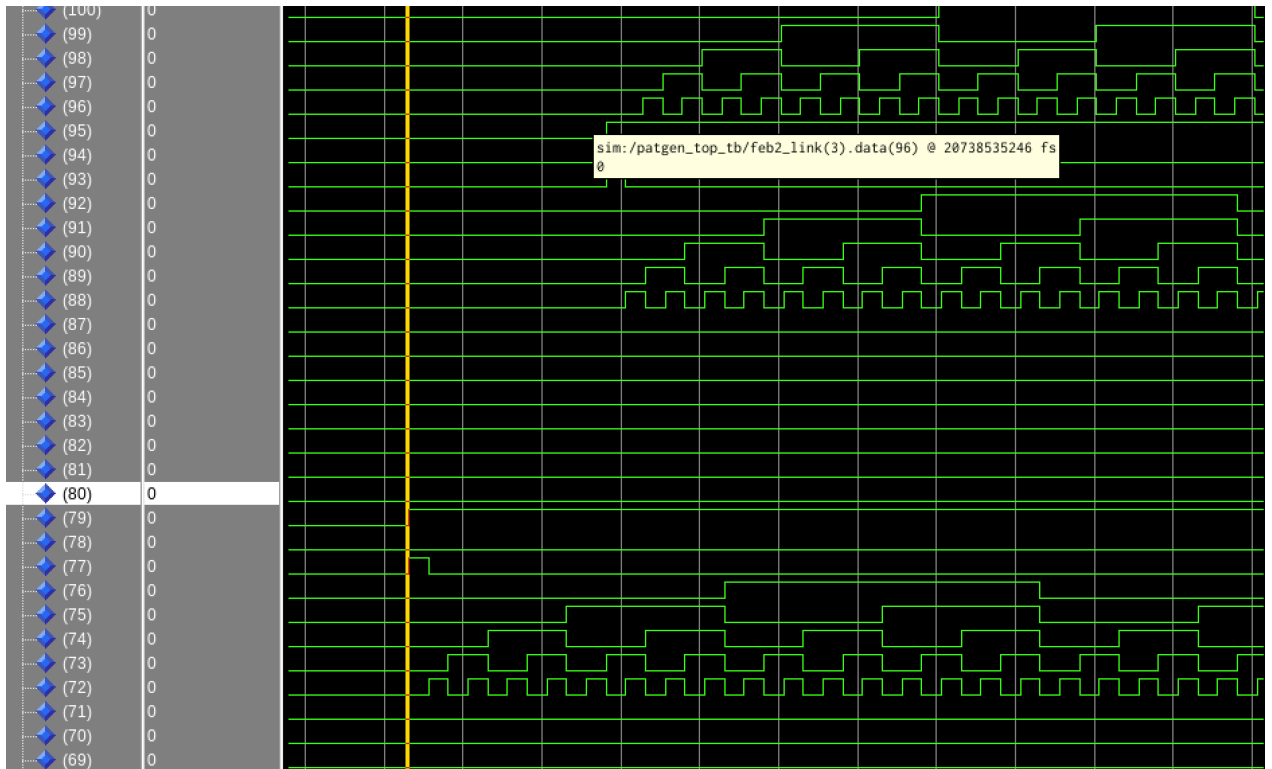


Figure 6. Example delay chains, with some signals coming earlier than others

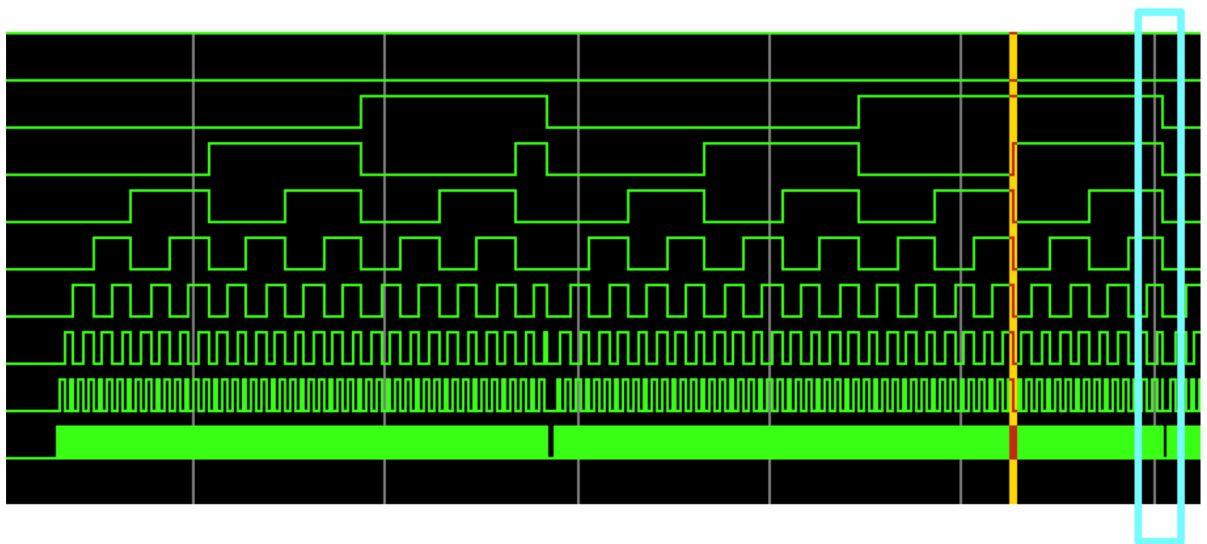


Figure 7. Example of an ADC channel having the correct fixed orbit highlighted by the last bit around the blue box.



Figure 8. Example of patgen running on a LASP Testboard.

335 trigger events in the ATLAS detector [3]. It ensures that data collection is synchronized across the
 336 various subsystems.

337 More specifically it will deliver the Level-0 trigger accept signal (L0a), which is based on
 338 coarse information about particle energy and position, to the LAr calorimeters [2].

339 Along side the L0a, The LASP receives a payload of data all through a component called the
 340 TTCRX from the outside world about particular triggered events. Similar to PATGEN, to test the
 341 LASP in the future would require us to have connections to the TTC incoming data, however relying
 342 on being connected to the outside world to debug internal components is not optimal. Instead want
 343 to be able to generate this signal internally. To do so we created the TTCGEN component to satisfy
 344 this need.

345 3.3.1 Requirements

346 The more explicit requirements of TTCGEN are outlined here.

347 1. Must provide a valid L0a, L0ID, LBID, ttype and BCID signals. Please see TTCRX firmware
 348 specification manual [2] for details on these signals.

349 (a) L0a must take the form of a BCID signal

350 (b) L0ID must be a 38 bit counter keeping track of every L0a that occurs

351 (c) LBID is the luminosity block id which is a counting the first bunch crossings.

352 (d) ttype is the trigger types that can be outputed by the trigger system.

353 2. A trigger must be set at random times to mimic real trigger system

354 3. The trigger must be a light weight implementation.

355 However, since the current use of slice test does not make use of the ttype and the LBID signals we
 356 will set those to be zero for the time being. Furthermore, to simplify the development, we created a
 357 minimal viable piece of firmware and so the trigger does not occur randomly instead it occurs every
 358 set number of frequencies. In otherwords we address points number 1, 3 first.

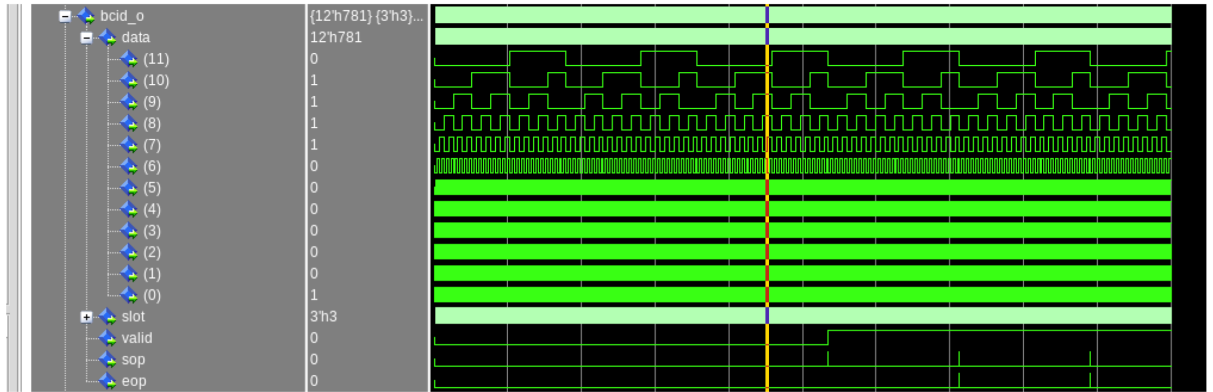


Figure 9. Example of TTCGEN bcid signal.

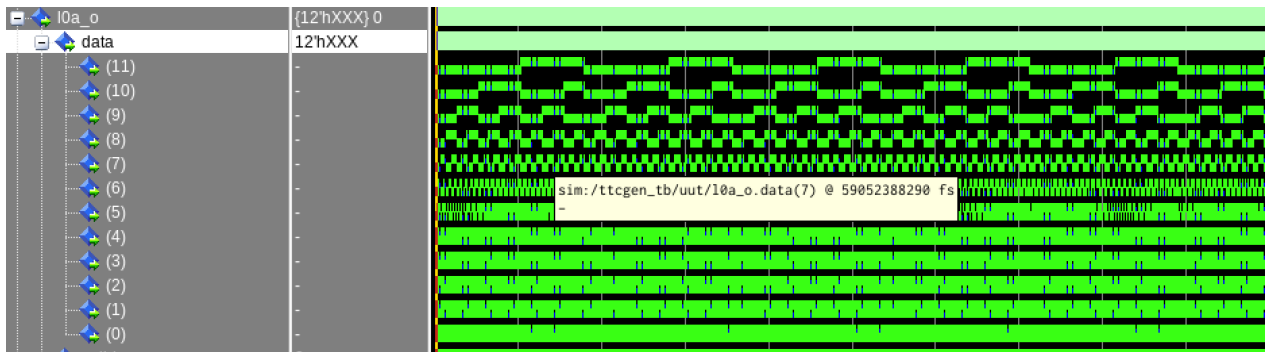


Figure 10. Example of TTCGEN L0a signal.

359 3.3.2 Simulation

360 For the simulation we want to first check that the BCID is of the correct format and is of the correct
 361 size and data shape. We expect the BCID to be a 12 bit counter increasing upwards with additional
 362 bits of for the valid, start of packet, end of packet and slot. Here we see figure 9 demonstrating that
 363 the BCID is in fact 12 bits long and that the data format contains the valid, eop (end of packet), sop
 364 (start of packet) signals matching the correct data format.

365 Secondly we want to check the TTCGEN is outputting the correct BCID's to trigger on. We
 366 expect the signals to be the same as the BCID signals except it contains regular splits of data where
 367 the trigger is not on. Here in figure 10 for demonstration purposes we trigger on every 10 cycles. We
 368 see that there are sections of the BCID where we loose data as expected since we are not triggering
 369 on all the data.

370 Lastly we want to check that L0ID is counting up for each of these triggers that occur. This is
 371 of 38 bit length data. We expect to see a simple counter. We demonstrate below that this is indeed
 372 the case 11.

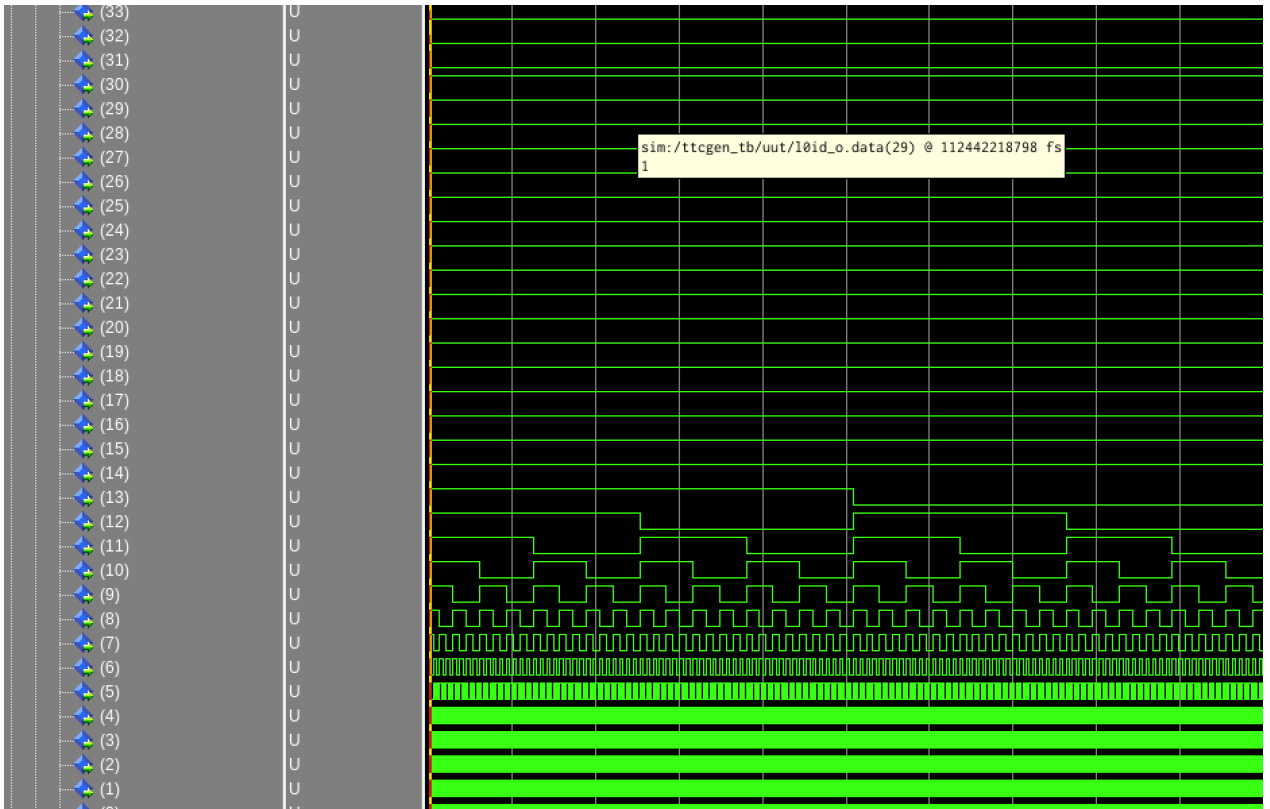


Figure 11. Example of TTCGEN L0ID signal. It is in fact counting upwards in synch with the L0a signal.

373 **3.3.3 Compilation**

374 As described previously we also compiled to the devkits and the LASP testboard and have success-
 375 fully completed both.

376 **3.4 10GBE Base R/KR**

377 Currently the connection between the 10 gigabit link between the Smart Rear Transition Module
 378 (SRTM) component. The SRTM unlike the current LASP uses a 10 gigabit BASE-KR network
 379 protocol in its network stack.

380 A network stack, also known as a networking protocol stack, is a layered set of software
 381 protocols and components that enable communication between devices over a network [1]. It's
 382 responsible for managing the flow of data between computers, servers, or any network-connected
 383 devices. The network stack follows a structured architecture, usually based on the OSI (Open
 384 Systems Interconnection) model or the TCP/IP model.

- 385 1. **Physical Layer:** This layer deals with the actual physical transmission of raw data bits over
 386 the communication medium, such as cables, wireless signals, and connectors. It defines
 387 characteristics like voltage levels, cable specifications, and physical topology.

- 388 2. **Data Link Layer:** Responsible for reliable point-to-point communication between directly
389 connected nodes. It handles error detection, flow control, and framing (dividing data into
390 frames). Ethernet and Wi-Fi protocols operate at this layer.
- 391 3. **Network Layer:** Focuses on routing packets of data from source to destination across
392 multiple networks. It involves addressing, routing, and logical network topology. IP (Internet
393 Protocol) operates here.
- 394 4. **Transport Layer:** Manages end-to-end communication and ensures reliable data delivery. It
395 divides data into smaller segments, performs error checking, and handles flow control. TCP
396 (Transmission Control Protocol) and UDP (User Datagram Protocol) operate here.
- 397 5. **Session Layer:** Establishes, maintains, and terminates communication sessions between
398 applications on different devices. It manages dialog control and synchronization between
399 processes.
- 400 6. **Presentation Layer:** Handles data translation, compression, and encryption, ensuring that
401 data sent by one application is understood by another. It also provides data formatting and
402 code conversion.
- 403 7. **Application Layer:** The topmost layer interacts directly with user applications. It provides
404 network services and application protocols for tasks such as file transfer (FTP), email (SMTP),
405 web browsing (HTTP), and more.

406 To demonstrate the network stack here is a diagram depicting such a network stack in figure
407 [12](#).

408 3.4.1 Simulation

409 For the simulation we took the existing network stack that has the BASE-R implementation of the
410 network stack and attempt to use the base-KR implementation of the PHY layer. However we will
411 only use one network stack and implement a loop back. Meaning the data sent to the transceiver
412 TX will then be connected to the receiver thus looping back the data. The result appears as follows.

413 We see all the signals are high for the RX/TX serial data and their respective 'ready' signals.
414 We also see that the various locks are all high except for the block_lock signal. We note that the
415 result is mostly promising except for the single lock signal.

416 3.4.2 Next Steps

417 After contacting Intel engineers for assistance¹, one of the suggestions was to instantiate two network
418 stacks instead of just one network stack. There is an apparent issue with the. However if one use
419 KR in loopback one have to set the nonce bit for the AN/LT to come up properly.

¹We reached out to peter.schepers@intel.com

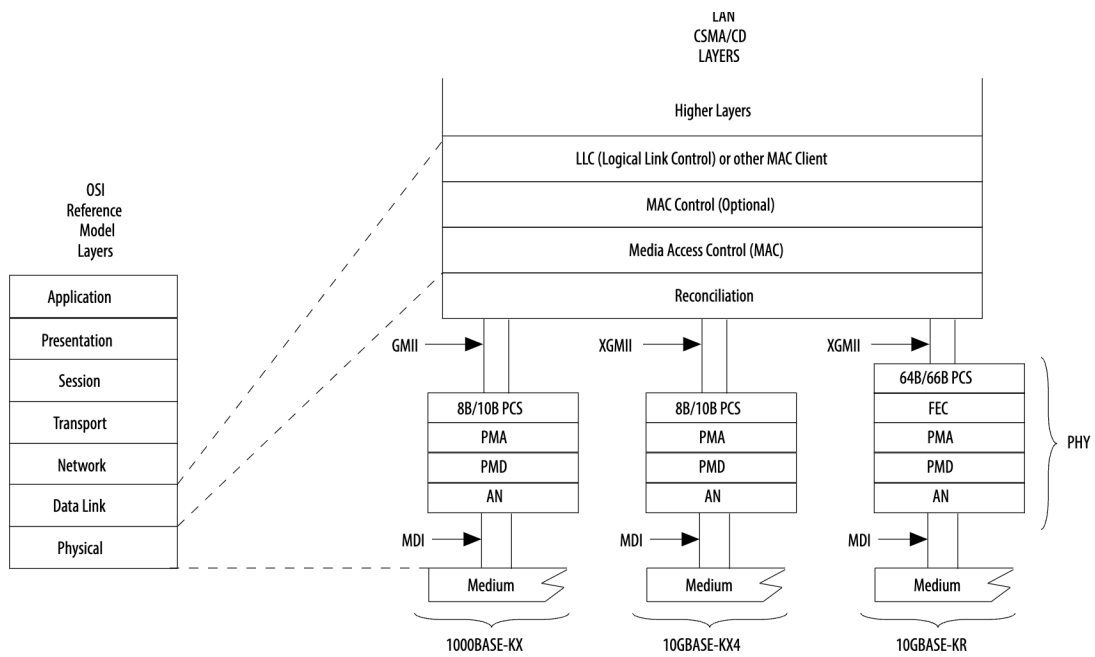


Figure 12. We see that the physical layer of the stack uses the base KR implementation that includes the MAC layers and the BASEKR layer.

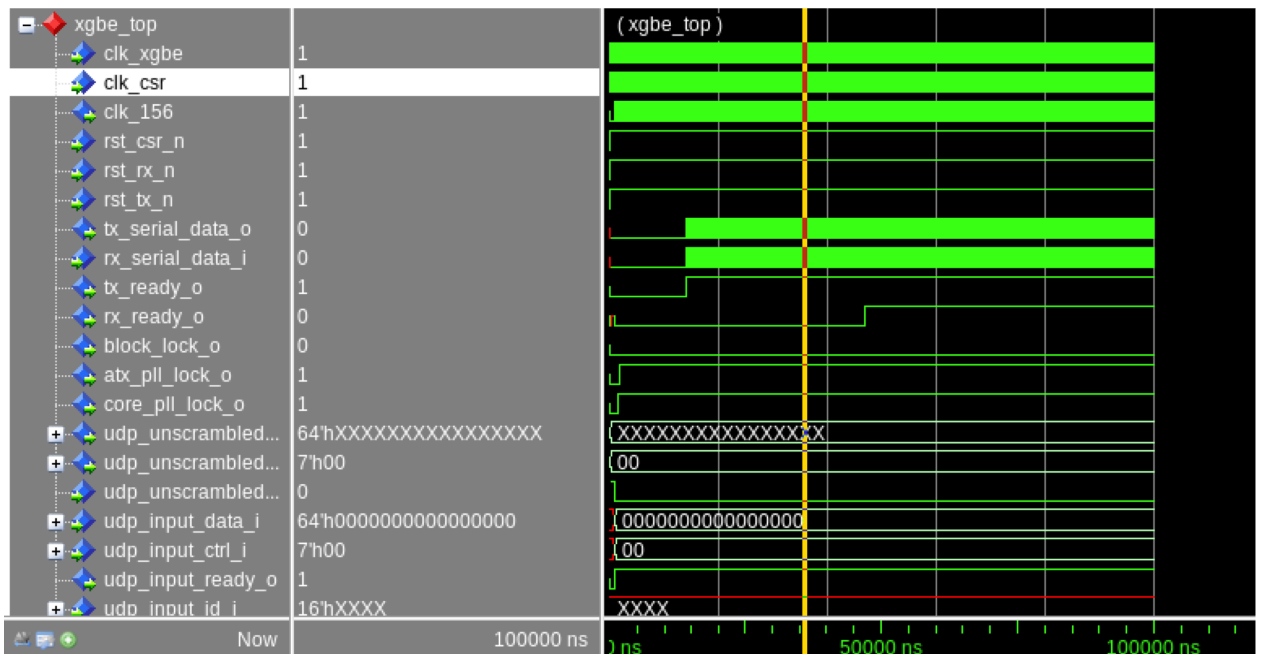


Figure 13. Example of BASE KR implementation of the network stack.

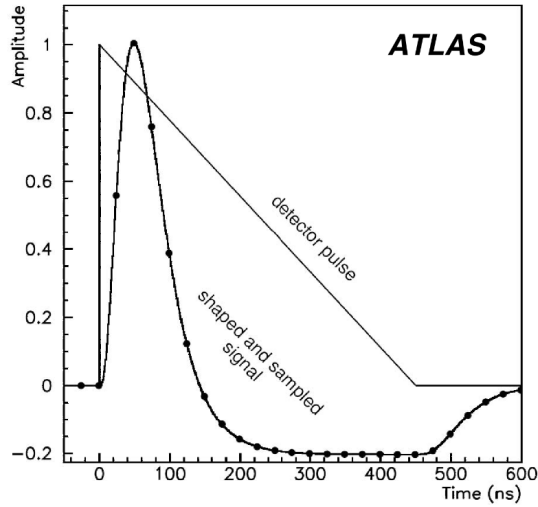


Figure 14. Example of the pulse shape that we wish to fit to [6].

420 4 Energy Reconstruction Algorithms

421 4.1 Optimal Filter

422 Calorimeters are detectors that measure the energy of particles by absorbing them and converting
 423 their energy into detectable signals. The optimal filter is responsible for accurately determining the
 424 energy of these particles based on the measured signals [5]. So here is a quick run down as to how
 425 the optimal filter works in energy reconstruction for calorimeters.

426 Firstly, calorimeters respond to incoming particles by generating electrical signals. The shape
 427 of the generated signal, known as the signal response function, depends on the type of particle and
 428 its energy. The optimal filter aims to find the best way to match the measured signals with the
 429 expected signal response [5].

430 Then we can look at deconvolution. We take the known shape of the energy deposition and fit
 431 the coefficients to match training data generated by a simulation. We use these optimal coefficients
 432 (a_{linear}) for computing the actual shape of the pulse.

433 Lastly we get a weighted sum. The optimal filter performs a weighted sum of the measured
 434 signal values, where the weights are determined by the deconvolution process. The goal is to empha-
 435 size the parts of the measured signal that best match the expected signal response. Mathematically
 436 it looks like the following:

$$O_t = \left(\sum_j^n a_{\text{linear}} V_{t-j} \right) \quad (4.1)$$

437 As mentioned before, the choice of filter weights is determined mathematically to maximize
 438 the signal-to-noise ratio. This means that the optimal filter amplifies the parts of the signal that
 439 carry the most information about the particle's energy while suppressing noise and other unwanted
 440 effects. This gives it the characteristic shape.

441 The optimal filter technique is used to improve the accuracy of energy reconstruction in
 442 calorimeters by taking into account the characteristics of the detector’s response and minimizing the
 443 impact of noise. This is crucial for particle physics experiments where precise energy measurements
 444 are necessary to study the properties of particles and phenomena. The technique requires a deep
 445 understanding of signal processing, detector physics, and mathematical optimization methods.

446 4.2 Motivation

447 The Optimal Filter is still robust in certain regimes of input data. Let us make use of the already
 448 simple model and add on to it small corrections. We fill in these small corrections by O which we
 449 model as a recurrent neural network.

450 However, since we know that we don’t care about the energy reconstruction *everywhere* but
 451 rather we care about the energy reconstruction at peaks where there’s high energy, we can selectively
 452 restrict the problem to just these special regimes. These regimes are controlled by the Γ ”gate”
 453 value by multiplying this correction term by 0 or 1. This gives us the structure we see in the equation
 454 above.

455 4.3 Optimal Filter Neural Network Correction

456 Let us fill in the missing blanks. We will work with a window size of m with n optimal filter
 457 coefficients.

- 458 1. We let O take in $m > n$ samples of ‘ADC’ data
- 459 2. We compute Optimal Filter from the most recent values, this case we have n coefficients so
 460 we take the n most recent ‘ADC’ data points and feed into the ‘OF’ model. Note: We keep
 461 track of the most recent m ‘OF’ outputs in memory.
- 462 3. We take the most recent n ‘OF’ outputs and feed them into the gate model

463 Let us formalize this more.

1. Compute ‘OF’

$$O_t = \left(\sum_j^n a_{\text{linear}} V_{t-j} \right)$$

2. Compute Gate, here we are using O as the saved m samples of O_t (optimal filter output)

$$\Gamma_t = \Gamma(O), \quad \Gamma : \mathbb{R}^m \rightarrow \mathbb{R}$$

3. Lastly we compute the Correction terms where $V_t \in \mathbb{R}^m$ is all the m samples of the ‘ADC’

$$O_j = O(V_t)_j, \quad O : \mathbb{R}^m \rightarrow \mathbb{R}^n$$

464 Okay enough talk, implement this. Let us first check how the optimal filter performs on high
 465 pileup data. See figure 15.

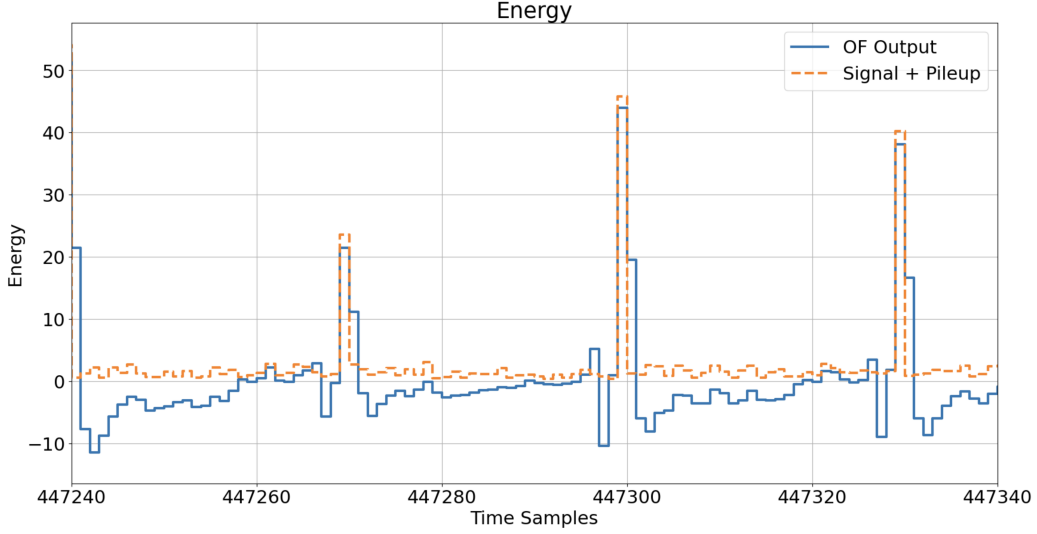


Figure 15. Example of optimal filter on high pileup data

466 Here we construct a neural network model that uses the optimal filter alongside a neural
 467 network correction term. However to train the neural network we compute minimize the variance
 468 of the error. This is because in general we do not care about a constant bias, we care only about
 469 minimizing the spread or the variation in the error. Thus we directly minimize such loss function.
 470 Consider y as the label, and we say p as the model including the optimal filter, and V as the input
 471 sample. And consider there to be n training samples then we have

$$\mathcal{L}(V, y) = \frac{\sum_i^n \left((p(V_i) - y_i) - \frac{1}{n} \sum_j^n p(V_j) - y_j \right)^2}{n - 1} \quad (4.2)$$

472 We minimize this using ADAM optimizer [7] and built the model using Keras [8]. The neural
 473 network model is a simple recurrent neural network with of 915 parameters. With 3 layers of 10
 474 hidden units.

475 A more descriptive diagram can be found here in figure 16.

476 4.4 Results

477 The initial results appear to have better performance than the classical Optimal Filter by an order
 478 of 40% improvement in reconstruction error. There is a reduce in the standard deviation in the
 479 errors between true energy and predicted energy. This is reflected in the plot of distribution of
 480 error 17. This approach is notably better than classical pure ML techniques (see figure 18), because
 481 of its computational efficiency and improved accuracy. Since there is a gate, the feed forward
 482 correction term (the computationally expensive term) is only calculated intermittently where as for
 483 other approaches using Convolutional Neural Networks these expensive forward propagation terms
 484 are computed multiple times. The code can be found here [repository](#).

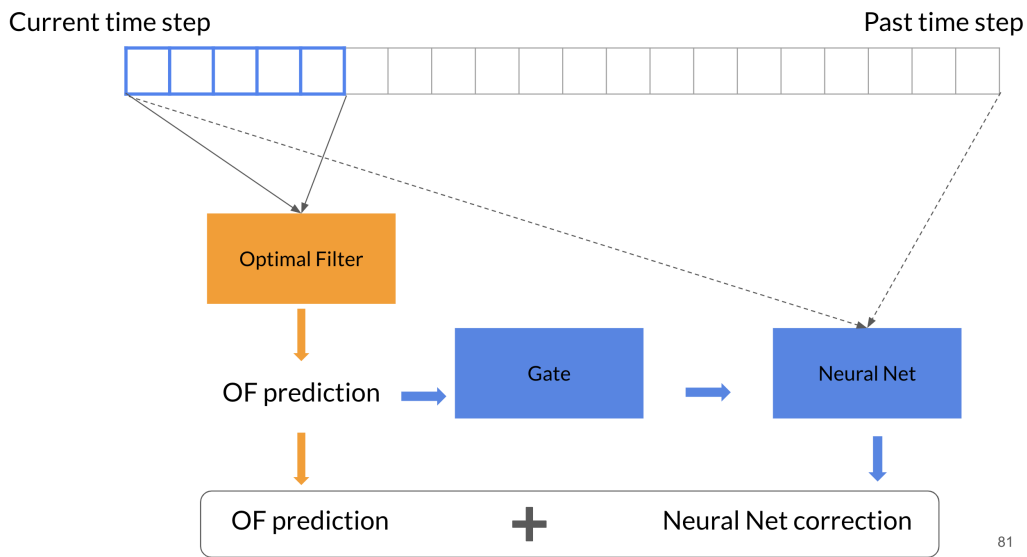


Figure 16. Example of neural network architecture. We see that the optimal filter takes in data as per usual, the output then gets fed into a gate which triggers the neural network correction term depending on its energy output. The results are then added together. Note that the neural network needs more data to be kept in memory on the order of 20 time samples, similar to a traditional convolutional neural network implementation.

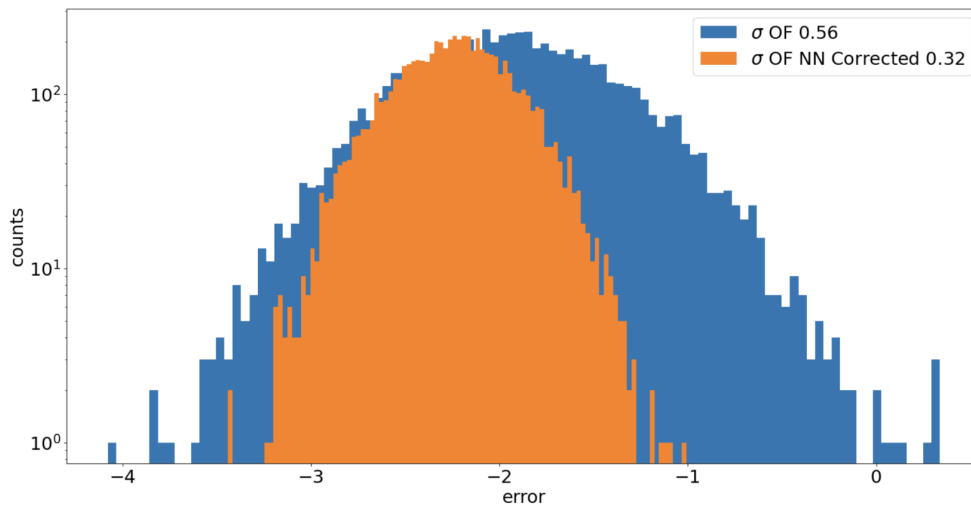


Figure 17. Histogram of computing true energy deposition minus predicted energy and we see that the spread or the standard deviation of the novel approach drastically improved the energy reconstruction error. The σ is the standard deviation of each error.

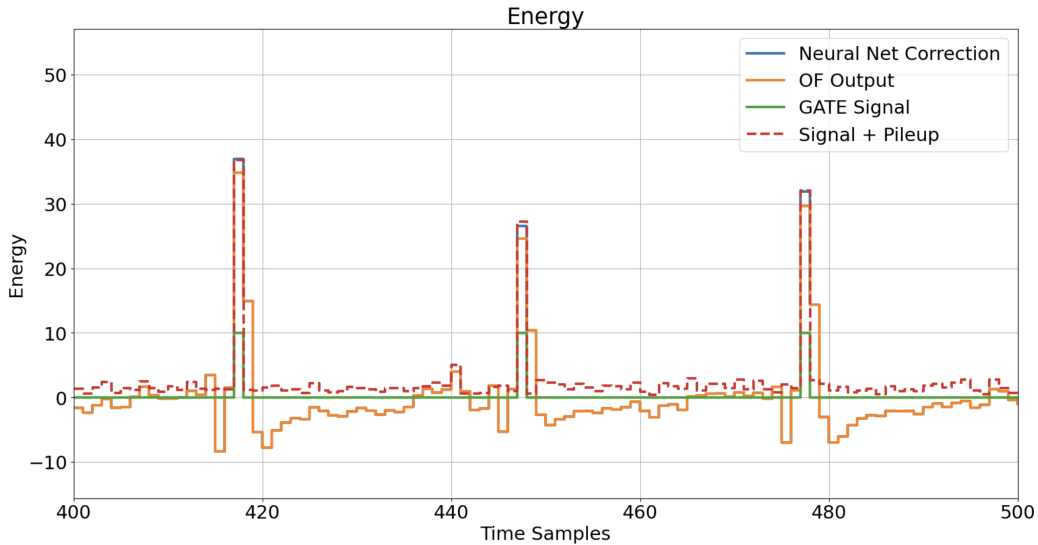


Figure 18. Visual check of the fit of our correction model. We see a noticeably better fit of the energy estimation than that of the traditional optimal filter.

485 5 Functional Tests

486 In this section we discuss the functional tests for the LASP board. One of the most important
 487 parts in the development is fabricating the physical board after designing all the firmware and the
 488 software to interface with the hardware components. However when building these boards from
 489 third-party suppliers it is up to us to help them determine the quality of their manufactured product
 490 and if these performances matches our expectations.

491 One of these performance tests is to test if the board is functional if at all immediately after
 492 they have been manufactured. This includes two key measurements, one of voltage and the second
 493 of the current. In this part of the project we discuss developing software interfaces and prototype
 494 circuits to conduct these tests.

495 5.1 National Instrument Data Acquisition

496 To measure the voltage or current using custom software defined tools we need to interface with
 497 the a data acquisition device. One such suitable device is the National Instrument (NI) cDAQ and
 498 its various modules used to control and acquire data.

499 For this project we use the special NIDAQMX python libaray to develop python scripts to measure
 500 and control and interface with the cDAQ, NI 9203 module for current measurements and the NI
 501 9205 module for voltage measurements and NI 9481 for relay control.

502 5.2 Voltage Measurements

503 5.2.1 Hardware Setup

504 We first describe the steps for setting up the circuits and hardware tools required for preforming a
 505 simple voltage measurement on a known power supply unit (PSU).

- 506 1. Turn on the DAQ by plugging it in with the USB connector and its power cable.

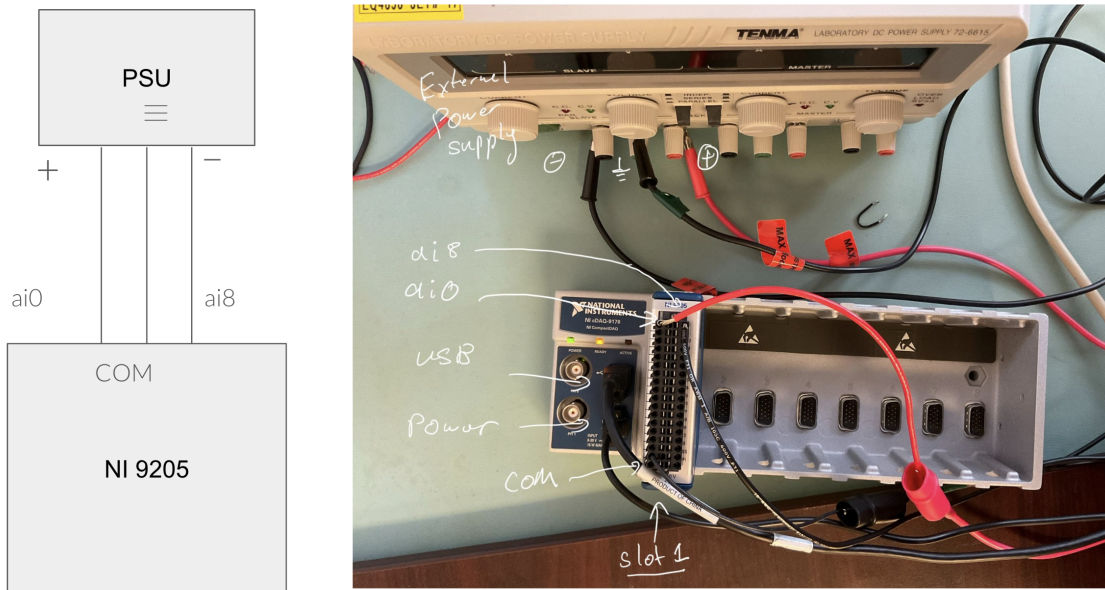


Figure 19. A graphical description of the hardware setup for our voltage measurement tests.

- 507 2. Take a power supply and route the positive leads to the ai0 channels. The negative leads come
 508 from the ai8 channels. (General Note: the negative leads come from the opposite end of the
 509 connectors)
- 510 3. We also want to ground the device so that our ground matches that of the power supply.
 511 Route a connection between the COM with the ground of the power supply. This makes the
 512 readings more accurate.

513 The circuit setup should look like the following description.

514 5.2.2 Software Setup

515 In the remaining parts of the project we developed the software components to interface with the
 516 NI cDAQ modules. Below is an example of our custom library interface.

```

517 1 from cDAQ import cDAQ_measurements
518 2
519 3 voltage_params = {"channel": ["cDAQ1mod1/ai0"], 'seconds': 20, 'sample_rate':
520 4 1000}
521 5 test = cDAQ_measurements(voltage_param=voltage_params)
522 6 test.measure()
523 7 test.save_csv_voltage("voltage_measure")
524 8 test.plot_voltage("voltage_measure")

```

Listing 1. Example interface for reading voltage measurements on the cDAQ NI 9205 module

525 This interface is supported by the package provided by the national instrument. To make all
 526 this work, please follow the [here](#).

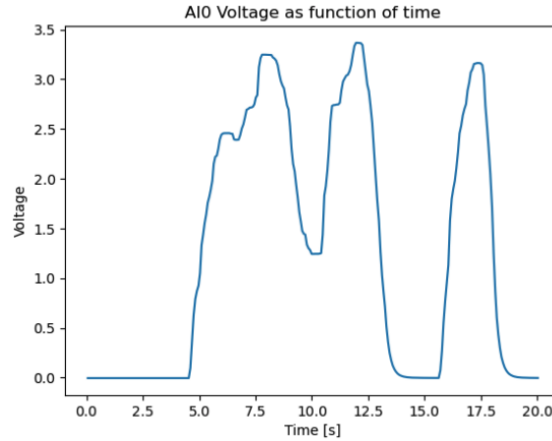


Figure 20. An example of voltage measurement conducted on a known power supply. Here we varied the voltage manually and see the recorded measurement reflect that manual variation.

Range	Accuracy at Full Scale	Random noise σ	Sensitivity
$\pm 10V$	$6,230 \mu V$	$237 \mu V$	$96.0 \mu V$
$\pm 5V$	$3,230 \mu V$	$121 \mu V$	$46.4 \mu V$
$\pm 1V$	$692 \mu V$	$29 \mu V$	$10.4 \mu V$
$\pm 0.2V$	$175 \mu V$	$15 \mu V$	$4 \mu V$

Table 1. The accuracy of the voltage measurements using the NI 9205 module.

527 The resulting voltage measurements can be plotted as presented below in 21.

528 However it is important to also note about the accuracy of the voltage measurement for each
 529 gain in voltage that we choose to measure.

530 5.3 Current Measurements

531 5.3.1 Hardware Setup

532 Similar to previous section we describe the steps for setting up the circuits and hardware tools
 533 required for performing a continuous live current measurement on a known power supply unit
 534 (PSU).

- 535 1. Turn on the DAQ by plugging it in with the USB connector and its power cable.
- 536 2. Take a power supply and route the positive leads to a potentiometer. We use the potentiometer
 537 to vary the current since the PSU cannot change the current.
- 538 3. We then connect potentiometer to the NI 9203 module in series putting the lead into ai0 and
 539 connecting ground to COM.

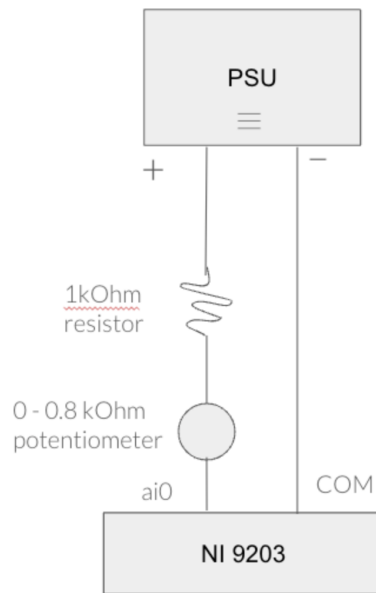


Figure 21. An example of voltage measurement conducted on a known power supply.

540 5.3.2 Software Setup

541 In the remaining parts of the project we developed the software components to interface that uses a
 542 live interface to display current measurements in a graphical interface. To do so run the following
 543 script. Please see [here](#) for a live demo of the GUI.

```

544 1 from cDAQ import cDAQ_measurements
545 2
546 3 current_params = {"channel": ["cDAQ1mod1/ai0"], 'seconds': 20, 'sample_rate':
547 4 1000}
548 5 test = cDAQ_measurements(current_param=current_params)
549 6 seconds = 60
550 7 test.multichan_current_live(seconds, ds = 0.2)

```

Listing 2. Example interface for live reading current measurements on the cDAQ NI 9203 module for 20 seconds with a sample refresh rate of 0.2 seconds

551 One of the technical challenges when building such a GUI, is an issue with buffering data and
 552 multi-threaded data acquisition. Since a single thread is allowed to read the data, we must then store
 553 the data in some buffer or memory. One way is to have 2 concurrent threads, one thread to read in
 554 data and buffering it and one to generate the GUI. We choose to do this because the NI cDAQ does
 555 not allow concurrent reading on a single cDAQ we have issues in recording data, hence we have a
 556 small gap in the time it takes to buffer the data meaning we loose data taking time momentarily. To
 557 mitigate its effects we create a third concurrent process that listens to a global variable. This third
 558 thread buffers the data into memory whenever this global variable is updated. This leaves the first
 559 thread free to read data again without having to manage memory. This trick although unsafe with
 560 higher refresh rates on the order of 10ms offers a decent compromise in providing a usable GUI
 561 that's accurate at higher sampling rates.

562 **6 Next Steps**

563 We hope that the continued development of the firmware, hardware testing and algorithms devel-
564 opment help move forward the develop of electronics for digital readouts on the LAr. Next steps
565 would be to further integrate these changes into the LASP framework allowing for faster testing and
566 debugging of future projects to come.

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